



Parameters	Ratings	Units
Blocking Voltage	350	$V_P$
Load Current	120	$mA_{rms} / mA_{DC}$
On-Resistance (max)	35	$\Omega$

### Features

- 3750V<sub>rms</sub> Input/Output Isolation
- 1-Form-C Solid State Relay
- Low Drive Power Requirements (TTL/CMOS Compatible)
- High Reliability
- Arc-Free With No Snubbing Circuits
- FCC Compatible
- VDE Compatible
- No EMI/RFI Generation
- Small 8-pin Packages
- Machine Insertable, Wave Solderable
- Surface Mount Tape & Reel Versions Available

### Applications

- Telecommunications
  - Telecom Switching
  - Tip/Ring Circuits
  - Modem Switching (Laptop, Notebook, Pocket Size)
- Hook Switch
- Dial Pulsing
- Ground Start
- Ringing Injection
- Instrumentation
  - Multiplexers
  - Data Acquisition
  - Electronic Switching
  - I/O Subsystems
- Meters (Watt-Hour, Water, Gas)
- Medical Equipment—Patient/Equipment Isolation
- Security
- Aerospace
- Industrial Controls

### Description

LCC110P is a 350V, 120mA, 35 $\Omega$ , 1-Form-C relay. This device is ideal for applications where a signal needs to be switched between two different lines. The small 8-lead package makes it an ideal space-saving replacement for a 1-Form-C electromechanical relay (EMR).

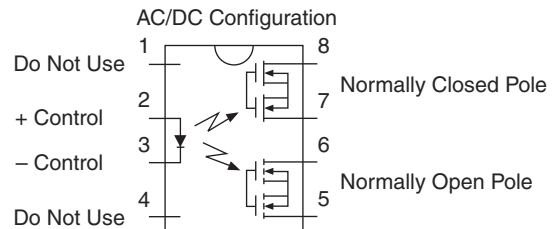
### Approvals

- UL Recognized Component: File E76270
- CSA Certified Component: Certificate 1175739
- EN/IEC 60950-1 Certified Component: TUV Certificate B 09 07 49410 004

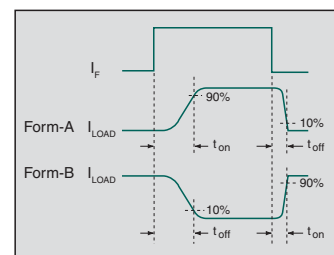
### Ordering Information

Part #	Description
LCC110	8-Pin DIP (50/Tube)
LCC110P	8-Pin Flatpack (50/Tube)
LCC110PTR	8-Pin Flatpack Tape & Reel (1000/Reel)
LCC110S	8-Pin Surface Mount (50/Tube)
LCC110STR	8-Pin Surface Mount Tape & Reel (1000/Reel)

### Pin Configuration



### Switching Characteristics for a 1-Form-C Device



### Absolute Maximum Ratings @ 25°C

Parameter	Min	Max	Unit
Blocking Voltage	-	350	V <sub>P</sub>
Reverse Input Voltage	-	5	V
Input control Current	-	50	mA
Peak (10ms)	-	1	A
Input Power Dissipation <sup>1</sup>	-	150	mW
Total Power Dissipation <sup>2</sup>	-	800	mW
Isolation Voltage, Input to Output	3750	-	V <sub>rms</sub>
Operating Temperature	-40	+85	°C
Storage Temperature	-40	+125	°C

Absolute Maximum Ratings are stress ratings. Stresses in excess of these ratings can cause permanent damage to the device. Functional operation of the device at conditions beyond those indicated in the operational sections of this data sheet is not implied.

<sup>1</sup> Derate linearly 1.33mW / °C.

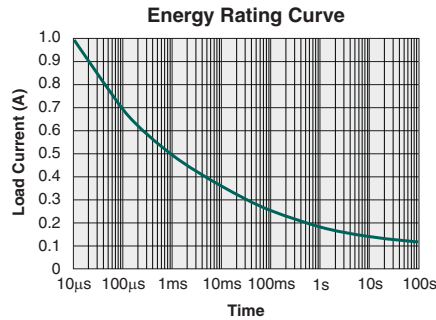
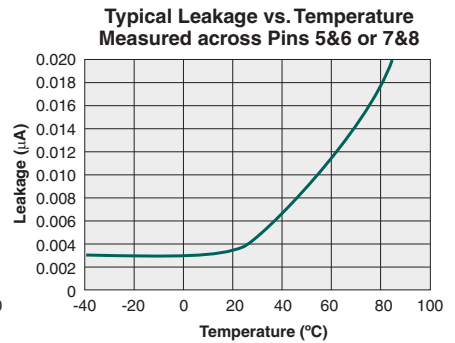
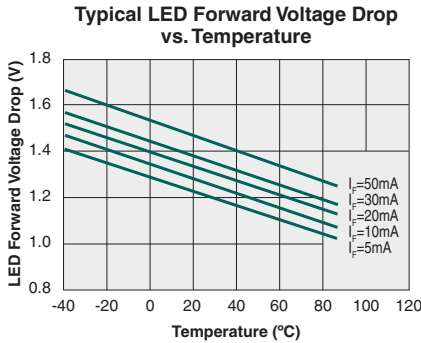
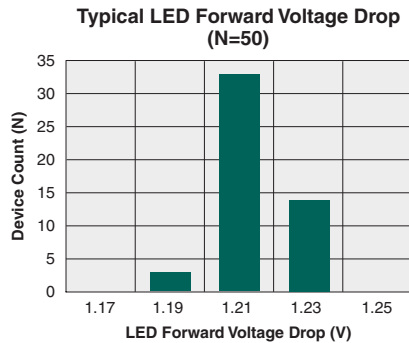
<sup>2</sup> Derate linearly 6.67mW / °C.

### Electrical Characteristics @ 25°C

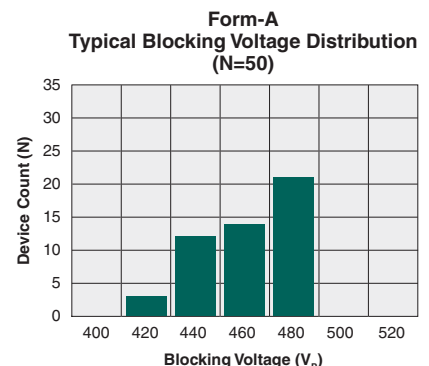
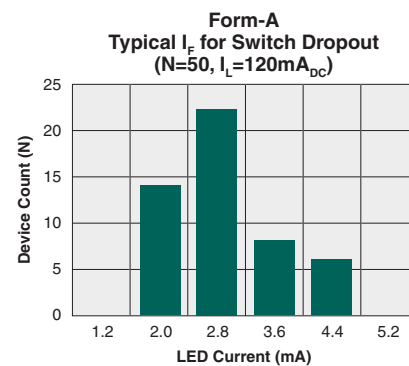
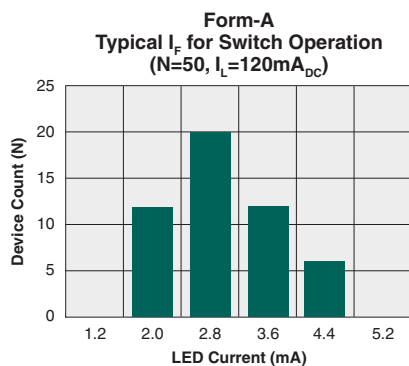
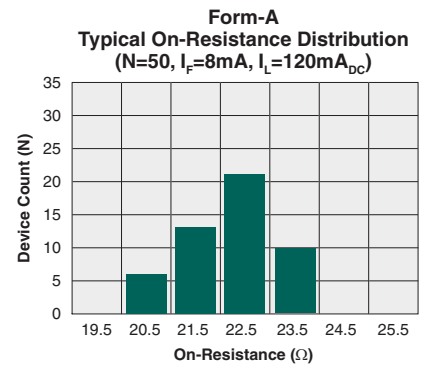
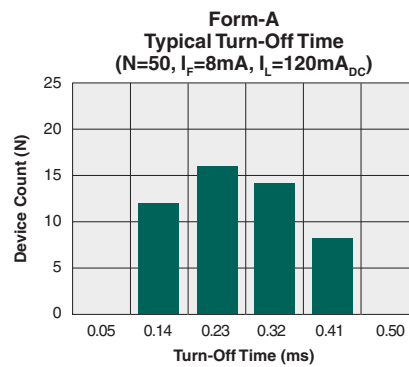
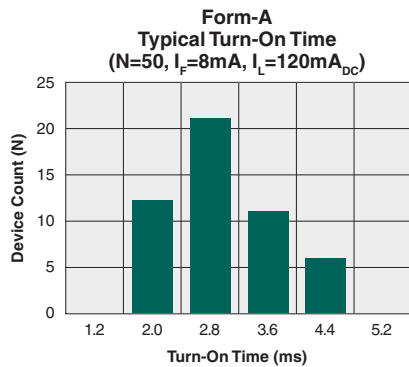
Parameter	Conditions	Symbol	Min	Typ	Max	Units
<b>Output Characteristics</b>						
Load Current						
Continuous, AC/DC Configuration	-	I <sub>L</sub>	-	-	120	mA <sub>rms</sub> / mA <sub>DC</sub>
Peak	t=10ms	I <sub>LPK</sub>	-	-	±350	mA <sub>P</sub>
On-Resistance, AC/DC Configuration	I <sub>L</sub> =120mA	R <sub>ON</sub>	-	23	35	Ω
Off-State Leakage Current	V <sub>L</sub> =350V <sub>P</sub>	I <sub>LEAK</sub>	-	-	1	μA
Switching Speeds						
Turn-On	I <sub>F</sub> =8mA, V <sub>L</sub> =10V	t <sub>on</sub>	-	-	4	ms
Turn-Off		t <sub>off</sub>	-	-	4	
Output Capacitance	V <sub>L</sub> =50V, f=1MHz	C <sub>OUT</sub>	-	25	-	pF
<b>Input Characteristics</b>						
Input Control Current to Activate	I <sub>L</sub> =120mA	I <sub>F</sub>	-	-	8	mA
Input Control Current to Deactivate	-	I <sub>F</sub>	0.4	0.7	-	mA
Input Voltage Drop	I <sub>F</sub> =8mA	V <sub>F</sub>	0.9	1.2	1.4	V
Reverse Input Current	V <sub>R</sub> =5V	I <sub>R</sub>	-	-	10	μA
<b>Common Characteristics</b>						
Capacitance, Input to Output	-	C <sub>I/O</sub>	-	3	-	pF

Note: If both poles operate simultaneously, then load current must be derated in order not to exceed package power dissipation value.

**COMMON PERFORMANCE DATA @25°C (Unless Otherwise Noted)\***



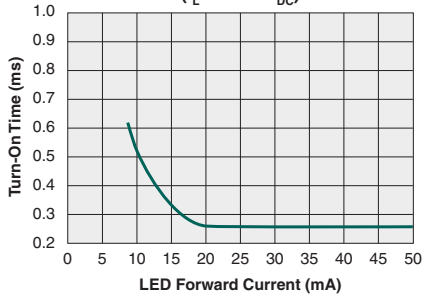
**FORM-A RELAY PERFORMANCE DATA @25°C (Unless Otherwise Noted)\***



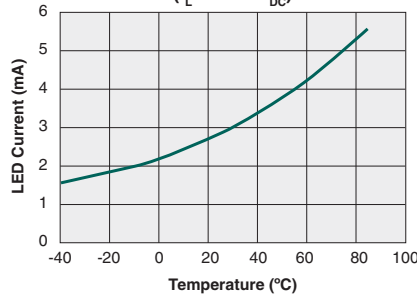
\*The Performance data shown in the graphs above is typical of device performance. For guaranteed parameters not indicated in the written specifications, please contact our application department.

**FORM-A RELAY PERFORMANCE DATA @25°C (Unless Otherwise Noted)\***

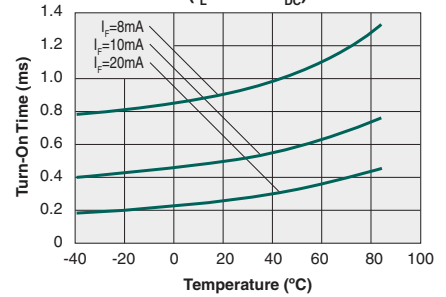
**Form-A**  
Typical Turn-On Time  
vs. LED Forward Current  
( $I_L=120mA_{DC}$ )



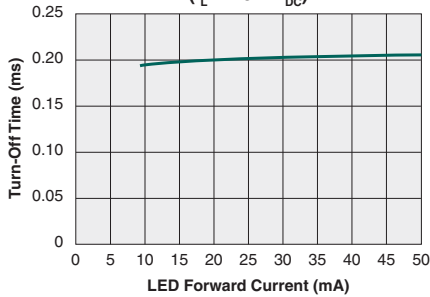
**Form-A**  
Typical  $I_F$  for Switch Operation  
vs. Temperature  
( $I_L=120mA_{DC}$ )



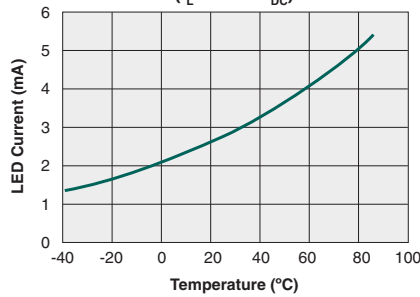
**Form-A**  
Typical Turn-On Time  
vs. Temperature  
( $I_L=120mA_{DC}$ )



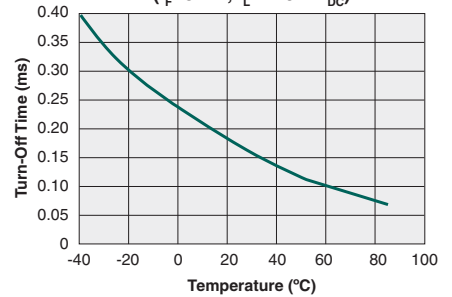
**Form-A**  
Typical Turn-Off Time  
vs. LED Forward Current  
( $I_L=120mA_{DC}$ )



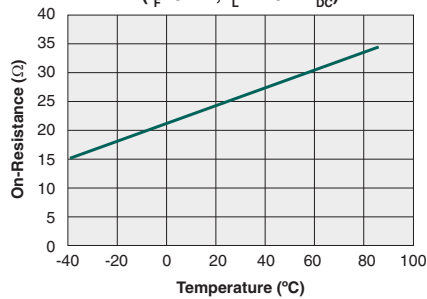
**Form-A**  
Typical  $I_F$  for Switch Dropout  
vs. Temperature  
( $I_L=120mA_{DC}$ )



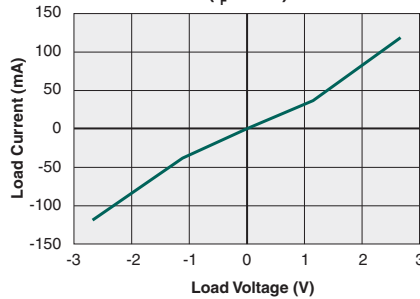
**Form-A**  
Typical Turn-Off Time  
vs. Temperature  
( $I_F=5mA, I_L=120mA_{DC}$ )



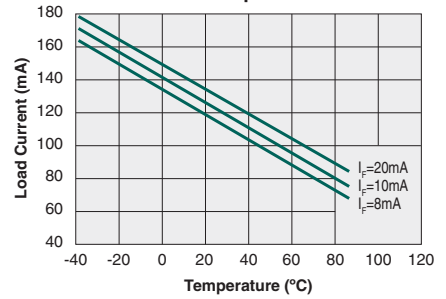
**Form-A**  
Typical On-Resistance  
vs. Temperature  
( $I_F=8mA, I_L=120mA_{DC}$ )



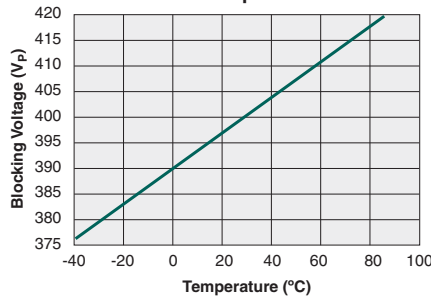
**Form-A**  
Typical Load Current vs. Load Voltage  
( $I_F=8mA$ )



**Form-A**  
Maximum Load Current  
vs. Temperature

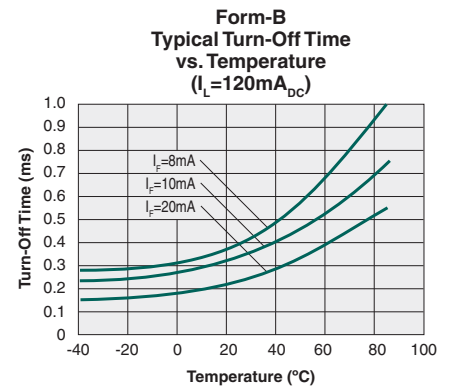
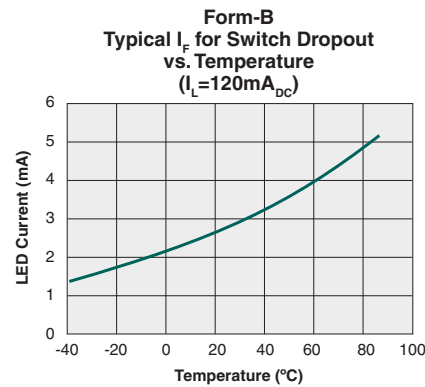
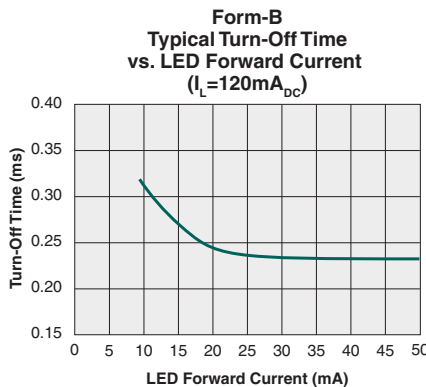
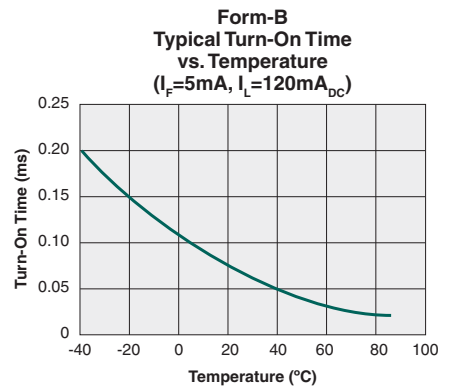
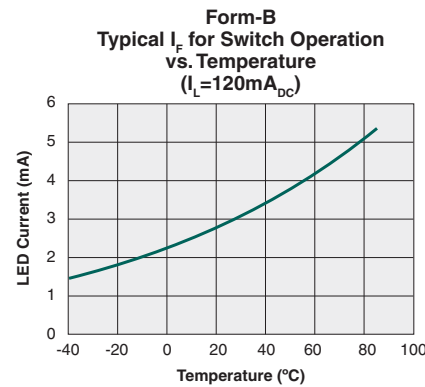
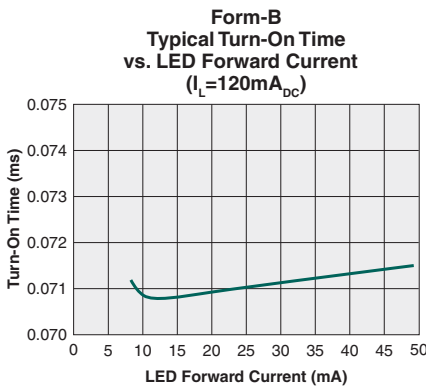
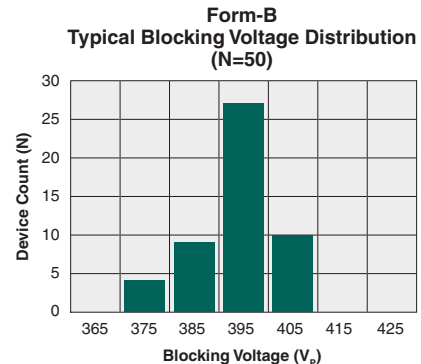
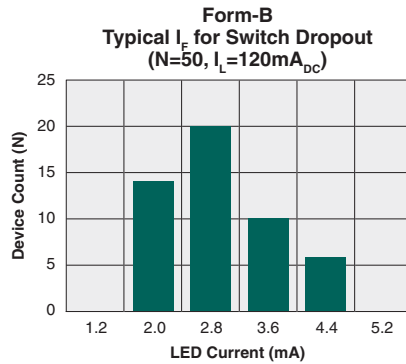
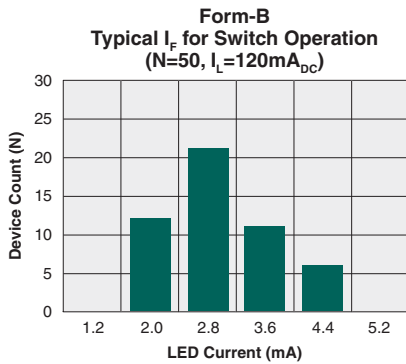
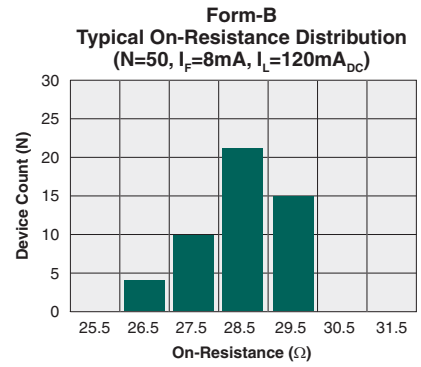
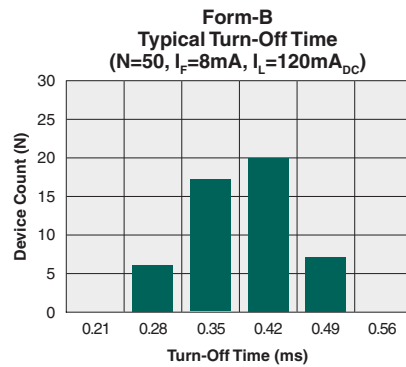
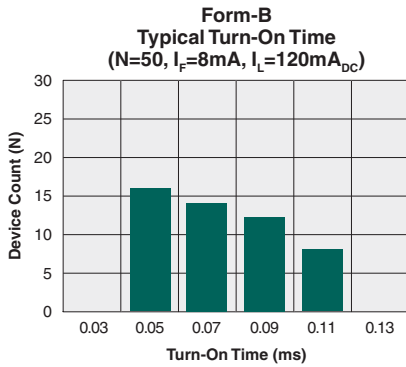


**Form-A**  
Typical Blocking Voltage  
vs. Temperature



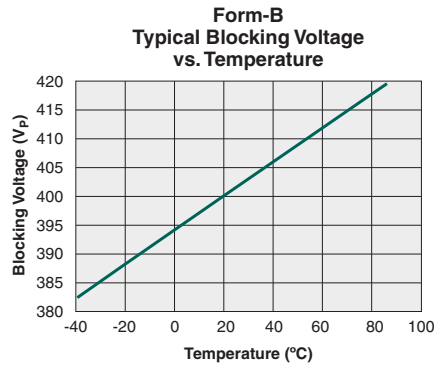
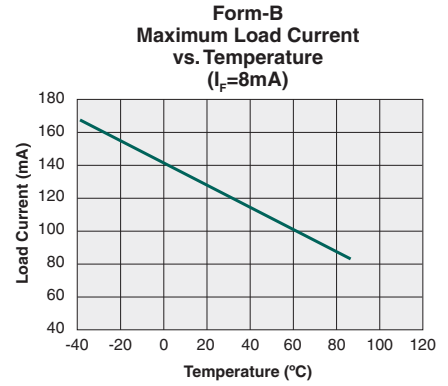
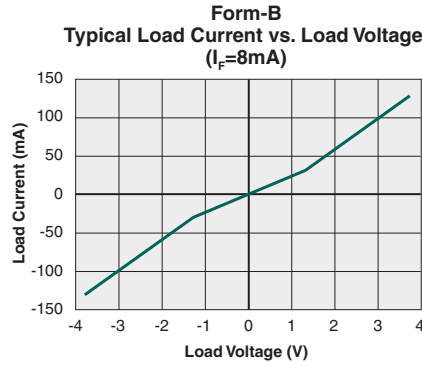
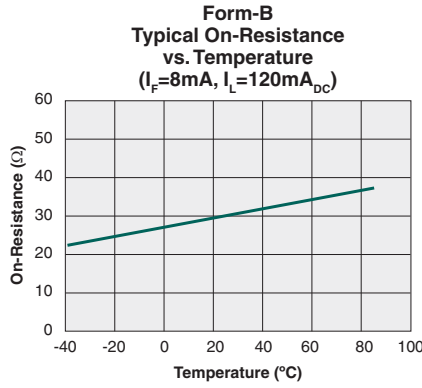
\*The Performance data shown in the graphs above is typical of device performance. For guaranteed parameters not indicated in the written specifications, please contact our application department.

**FORM-B RELAY PERFORMANCE DATA @25°C (Unless Otherwise Noted)\***



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**FORM-B RELAY PERFORMANCE DATA @25°C (Unless Otherwise Noted)\***



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## Manufacturing Information

### Moisture Sensitivity



All plastic encapsulated semiconductor packages are susceptible to moisture ingress. IXYS Integrated Circuits Division classified all of its plastic encapsulated devices for moisture sensitivity according to the latest version of the joint industry standard, **IPC/JEDEC J-STD-020**, in force at the time of product evaluation. We test all of our products to the maximum conditions set forth in the standard, and guarantee proper operation of our devices when handled according to the limitations and information in that standard as well as to any limitations set forth in the information or standards referenced below.

Failure to adhere to the warnings or limitations as established by the listed specifications could result in reduced product performance, reduction of operable life, and/or reduction of overall reliability.

This product carries a **Moisture Sensitivity Level (MSL) rating** as shown below, and should be handled according to the requirements of the latest version of the joint industry standard **IPC/JEDEC J-STD-033**.

Device	Moisture Sensitivity Level (MSL) Rating
LCC110 / LCC110S / LCC110P	MSL 1

### ESD Sensitivity



This product is **ESD Sensitive**, and should be handled according to the industry standard **JESD-625**.

### Reflow Profile

This product has a maximum body temperature and time rating as shown below. All other guidelines of **J-STD-020** must be observed.

Device	Maximum Temperature x Time
LCC110 / LCC110S	250°C for 30 seconds
LCC110P	260°C for 30 seconds

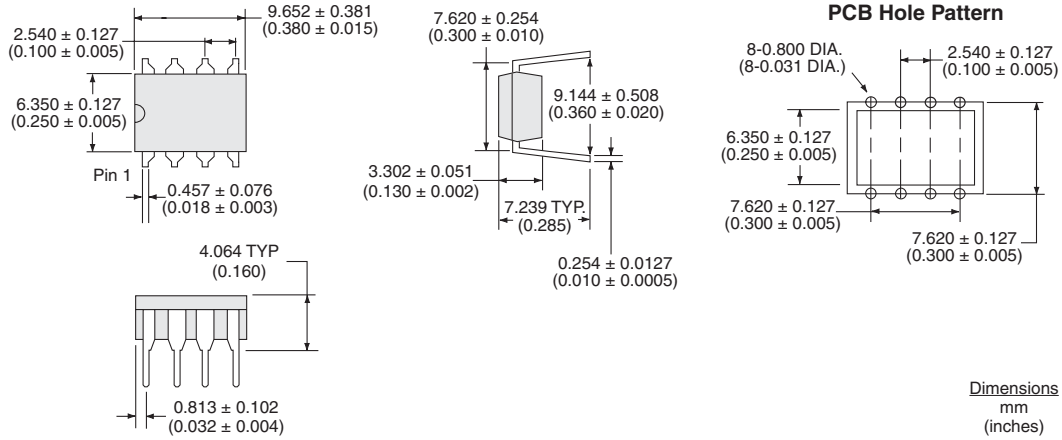
### Board Wash

IXYS Integrated Circuits Division recommends the use of no-clean flux formulations. However, board washing to remove flux residue is acceptable. Since IXYS Integrated Circuits Division employs the use of silicone coating as an optical waveguide in many of its optically isolated products, the use of a short drying bake could be necessary if a wash is used after solder reflow processes. Chlorine- or Fluorine-based solvents or fluxes should not be used. Cleaning methods that employ ultrasonic energy should not be used.

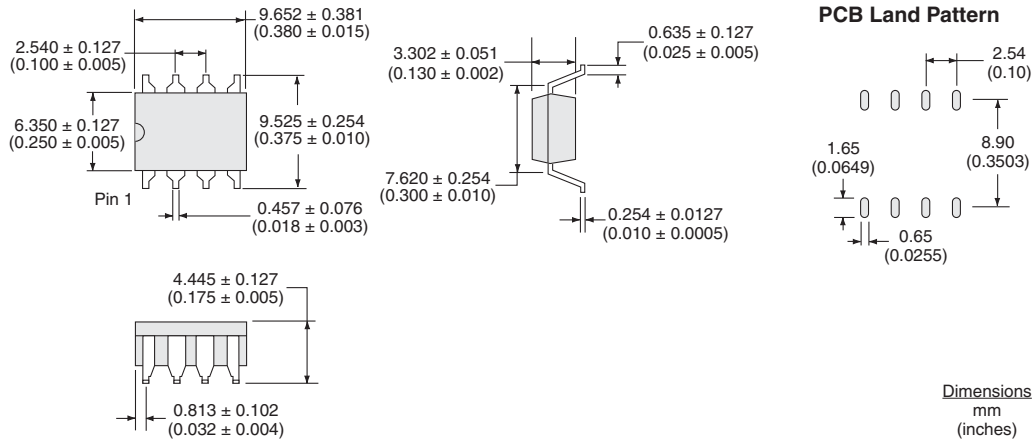


**Mechanical Dimensions**

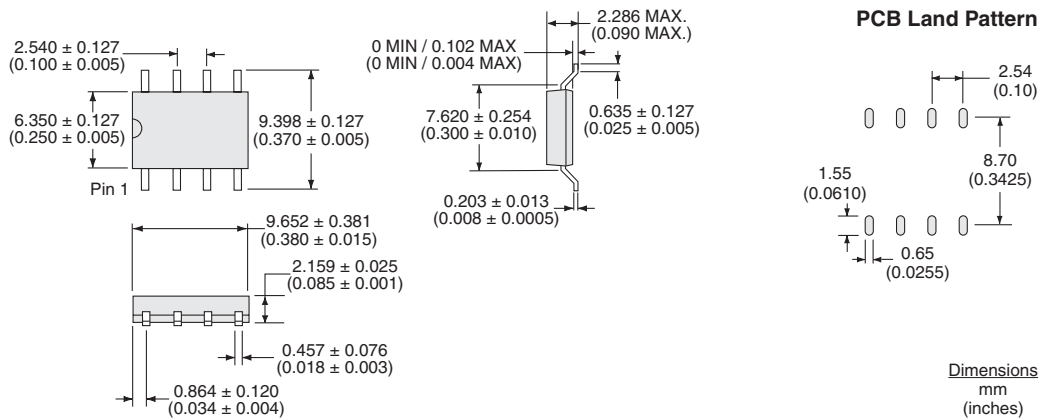
**LCC110**



**LCC110S**

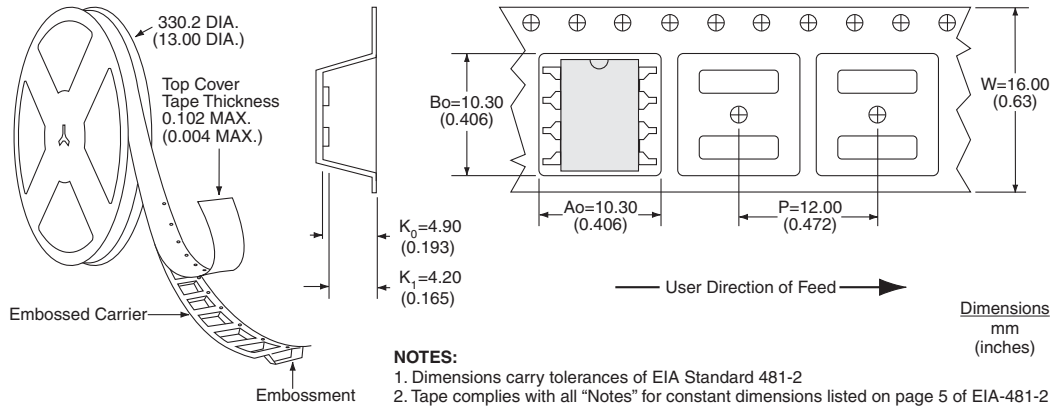


**LCC110P**

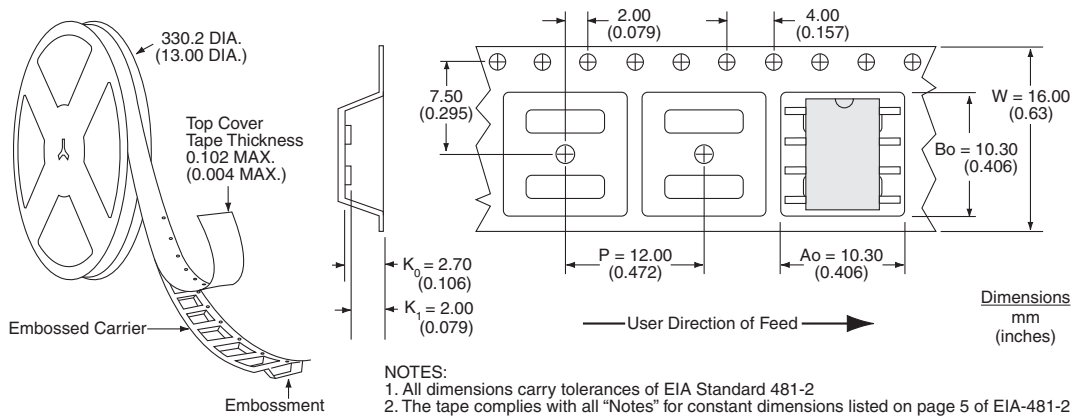




### LCC110STR Tape & Reel



### LCC110PTR Tape & Reel



For additional information please visit our website at: [www.ixysic.com](http://www.ixysic.com)

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